



RFIC 2026 Call for Papers

RFIC2026 | 7 – 9 June 2026 | rfic-ieee.org

Thomas Michael Menino Convention & Exhibition Center, Boston, MA

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The 2026 IEEE Radio Frequency Integrated Circuits Symposium (RFIC 2026) is the premier forum focused exclusively on presenting the latest research results in RF, millimeter-wave, and wireless integrated circuits.

Technical Areas: The symposium solicits papers describing original work in all areas related to RF, mm-Wave, THz, and wireless systems and ICs. Work must be demonstrated through IC hardware results and measurements.

- **(NEW) Industry and Start-ups:** RFIC and mm-Wave circuit and system design techniques and demonstrations for commercial applications in various areas of RFIC and mm-Wave including products or R&D for productization or new concepts and ideas from start-ups targeting commercial products.
- **Sub-D band mm-Wave Circuits:** >20GHz <110GHz circuits for wireless communication, including phase shifters, phased arrays, beamformers, MIMO transceivers, and other systems for 5G applications.
- **D-band Circuits:** >110GHz circuits and SOCs for wireless communication, including transceivers, transmitters, and other systems for 6G applications.
- **Transmitters and Power Amplifiers:** for RF through mm-Wave, and higher frequencies, power amplifiers, drivers, modulators, digital transmitters, advanced TX circuits, linearization, and efficiency enhancement techniques.
- **Front-End Circuits:** LNAs, mixers, VGAs, T/R switches, integrated FEM, amplifiers, filters, and demodulators.
- **Wireline, Optical, Quantum and Mixed-Signal Circuits:** baseband and RF converters (ADC/DAC), sub-sampling/over-sampling circuits, converters for digital beamforming or emerging architectures, power (DC-DC) converters for RF applications, conversion techniques for wireline or optical connectivity (I/O transceivers and CDRs), silicon photonics, quantum computing ICs, hardware security, and AI applied to RF circuits.
- **Oscillators and Frequency Synthesizers:** for RF through mm-Wave frequencies, D-band and higher, VCOs, injection-locking frequency dividers/multipliers, PLLs, DLLs, MDLLs, DDS, LO drivers, and frequency dividers.
- **Device/Packaging/Modeling and Testing Technologies:** RF device technology (both silicon and compound semiconductors), MEMs, integrated passives, photonic technologies, reliability, packaging, modeling and testing, EM modeling/co-simulation, built-in-self-test (BIST), 3D ICs, and novel THz solutions.

- **Wireless Radios and Systems-on-Chip:** innovative circuit and system-on-chip concepts related to software-defined radio, interference cancellation, full-duplex, cellular/WiFi, GPS, low-power radio circuits for sensors, IoT and biomedical applications, radio architectures suitable for energy harvesting, wake-up receivers, etc.
- **Radar, Imager, and Sensor:** integrated and vehicular radar, imaging, spectroscopy, MEMs-based sensors and actuators, and sensing circuits at RF through THz frequencies.
- **RFIC Integrated System Applications:** system-level innovations in RFICs with application to 5G and 6G, radar, imaging, satellite communications, terahertz, biomedical, and optoelectronic systems. May include interactive demonstration and presentation of **complete systems based on new or previously published chips**.

Format and Location: The 2026 symposium is an in-person conference. Events will be held at the Thomas Michael Menino Convention and Exhibition Center in Boston, MA, USA. RFIC 2026 starts on Sunday, June 7, 2026, with workshops followed by two plenary talks and a reception featuring our top industry and student papers. Monday and Tuesday, June 8-9 will comprise oral presentations and panel sessions culminating in a closing student event.

IMS 2026: RFIC 2026 kicks off a refreshed and reorganized IMS 2026. The week continues with two new symposia formed out of traditional IMS technical content: the IEEE RF Technology & techniques (RFTT) and IEEE RF Systems & Applications (RFSA) Symposium, and completes the week with the ARFTG Microwave Measurement Conference (ARFTG). This week is the world's largest and most important gathering of RF and microwave professionals in the field with more than 9000 participants.

Industry Exhibition: A three-day Exhibition typically showcases more than 900 Exhibitors who represent the state-of-the-art of the industry covering everything needed for RF and microwave design. More on the format of the 2026 Exhibition is found on both RFIC and IMS websites.

Electronic Submission Deadlines

Manuscript in PDF format: **January 6, 2026**

Final Manuscripts for the RFIC Digest: **March 20, 2026**

All submissions must be made at rfic-ieee.org in pdf form.

